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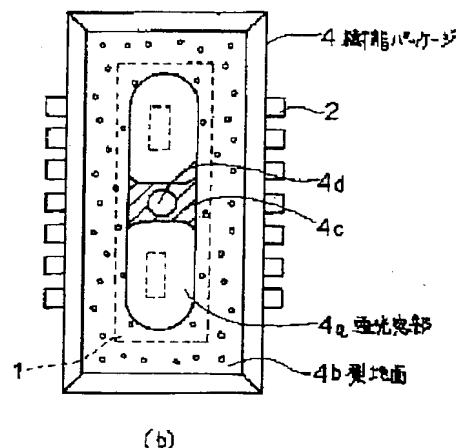
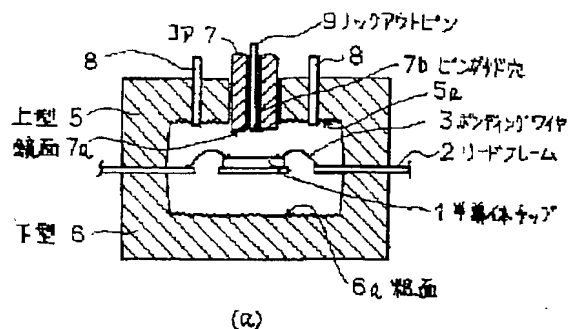
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TITLE : DIE FOR MOLDING TRANSPARENT  
 RESIN SEALING-TYPE  
 SEMICONDUCTOR DEVICE



ABSTRACT : PURPOSE: To make it easy to part the mirror surface of a core and the smooth light transmission window of a transparent resin package which comes into close contact with the mirror surface from a die immediately after molding and prevent the resin package from becoming warped and deformed when parting it from the die by assembling a knock-out pin into the core which forms the light transmission window in the resin package.

CONSTITUTION: A knock-out pin 9 for parting from a die is assembled into a molding die in such a manner that the pin 9 is interconnected to knock-out pins 8 on both sides of a core 7 and is allowed to protrude together with the pins 8. A molding material is injected into this molding die to transfer-mold the transparent resin package 4 of a semiconductor device, and the resin package 4 is pushed by the knock-out pins 8, 9 to part the package 4 from the die by opening the die and thrusting the knock-out pins 8, 9 simultaneously. In this case, an air introduced from an atmosphere through a thin clearance between the knock-out pin 9 for parting from the die and the core 7, finds its way into a space between the light transmission window 4 of the resin package 4 and the mirror surface 7a of the core 7 which come into close contact with each other to assist in the separation of both surfaces.

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